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**SiC**

Silicon Carbide Diode

**5<sup>th</sup> Generation thinQ!<sup>TM</sup>**

650V SiC Schottky Diode

**IDW32G65C5B**

**Final Datasheet**

Rev. 2.0, 2015-04-13



## 5<sup>th</sup> Generation thinQ!™ SiC Schottky Diode

IDW32G65C5B

### 1 Description

ThinQ!™ Generation 5 represents Infineon leading edge technology for the SiC Schottky Barrier diodes. A combination with a new, more compact design and thin-wafer technology results in a new family of products showing improved efficiency over all load conditions, resulting from both the improved thermal characteristics and a lower figure of merit ( $Q_c \times V_f$ ).

The new thinQ!™ Generation 5 has been designed to complement our 650V CoolMOS™ families: this ensures meeting the most stringent application requirements in this voltage range.

#### Features

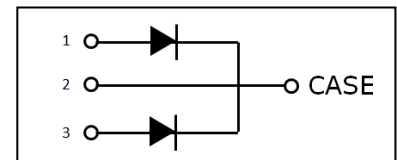
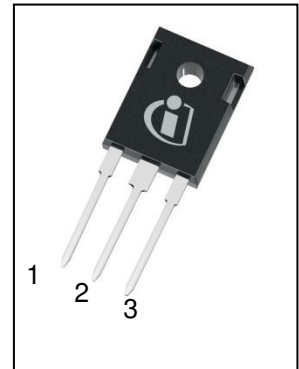
- Revolutionary semiconductor material - Silicon Carbide
- Benchmark switching behavior
- No reverse recovery/ No forward recovery
- Temperature independent switching behavior
- High surge current capability
- Pb-free lead plating; RoHS compliant
- Qualified according to JEDEC<sup>1)</sup> for target applications
- Breakdown voltage tested at 35 mA<sup>2) 3)</sup>
- Optimized for high temperature operation

#### Benefits

- System efficiency improvement over Si diodes
- System cost / size savings due to reduced cooling requirements
- Enabling higher frequency / increased power density solutions
- Higher system reliability due to lower operating temperatures
- Reduced EMI

#### Applications

- Switch mode power supply
- Power factor correction
- Solar inverter
- Uninterruptible power supply



**Table 1 Key Performance Parameters** <sup>4)</sup>

Parameter	Value	Unit
$V_{DC}$	650	V
$Q_C; V_R=400V$	2 x 23	nC
$E_C; V_R=400V$	2 x 5.4	μJ
$I_F @ T_C < 120^\circ C$	2 x 16	A

**Table 2 Pin Definition**

Pin 1	Pin 2	Pin 3
A	C	A

Type / ordering Code	Package	Marking	Related links
IDW32G65C5B	PG-TO247-3	D3265B5	<a href="http://www.infineon.com/sic">www.infineon.com/sic</a>

1) J-STD20 and JESD22

2) All devices tested under avalanche conditions for a time periode of 10ms

3) Per Leg

4) Per Device

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## 2 Maximum ratings

**Table 3** Maximum ratings

Parameter	Symbol	Values			Unit	Note/Test Condition
		Min.	Typ.	Max.		
Continuous forward current <sup>1)</sup>	$I_F$	–	–	16	A	$T_C < 120^\circ\text{C}$ , $D=1$
Surge non-repetitive forward current, sine halfwave <sup>1)</sup>	$I_{F,SM}$	–	–	95		$T_C = 25^\circ\text{C}$ , $t_p=10\text{ ms}$
		–	–	74		$T_C = 150^\circ\text{C}$ , $t_p=10\text{ ms}$
Non-repetitive peak forward current <sup>1)</sup>	$I_{F,max}$	–	–	637		$T_C = 25^\circ\text{C}$ , $t_p=10\text{ }\mu\text{s}$
$i^2t$ value <sup>1)</sup>	$\int i^2 dt$	–	–	45	A <sup>2</sup> s	$T_C = 25^\circ\text{C}$ , $t_p=10\text{ ms}$
		–	–	28		$T_C = 150^\circ\text{C}$ , $t_p=10\text{ ms}$
Repetitive peak reverse voltage	$V_{RRM}$	–	–	650	V	$T_j = 25^\circ\text{C}$
Diode dv/dt ruggedness	$dv/dt$	–	–	100	V/ns	$V_R=0..480\text{ V}$
Power dissipation <sup>2)</sup>	$P_{tot}$	–	–	188	W	$T_C = 25^\circ\text{C}$
Operating and storage temperature	$T_j, T_{stg}$	-55	–	175	°C	
Mounting torque		–	50	70	Ncm	M3 screws

## 3 Thermal characteristics

**Table 4** Thermal characteristics TO-247-3

Parameter	Symbol	Values			Unit	Note/Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction-case <sup>1)</sup>	$R_{thJC}$	–	1.2	1.6	K/W	lead
Thermal resistance, junction-ambient <sup>1)</sup>	$R_{thJA}$	–	–	62		
Soldering temperature, wavesoldering only allowed at leads	$T_{sold}$	–	–	260	°C	1.6mm (0.063 in.) from case for 10 s

1) Per Leg

2) Per Device

## Electrical characteristics

**Table 5** Static characteristics

Parameter	Symbol	Values			Unit	Note/Test Condition
		Min.	Typ.	Max.		
DC blocking voltage <sup>1)</sup>	$V_{DC}$	650	–	–	V	$T_j=25^{\circ}\text{C}$
Diode forward voltage <sup>1)</sup>	$V_F$	–	1.5	1.7		$I_F=16\text{ A}, T_j=25^{\circ}\text{C}$
		–	1.8	2.1		$I_F=16\text{ A}, T_j=150^{\circ}\text{C}$
Reverse current <sup>1)</sup>	$I_R$	–	0.8	200	$\mu\text{A}$	$V_R=650\text{ V}, T_j=25^{\circ}\text{C}$
		–	0.2	71		$V_R=600\text{ V}, T_j=25^{\circ}\text{C}$
		–	3.2	1400		$V_R=650\text{ V}, T_j=150^{\circ}\text{C}$

**Table 6** AC characteristics

Parameter	Symbol	Values			Unit	Note/Test Condition
		Min.	Typ.	Max.		
Total capacitive charge <sup>1)</sup>	$Q_c$	–	23		nC	$V_R=400\text{ V}, di/dt=200\text{ A}/\mu\text{s}, I_F \leq I_{F,MAX}, T_j=150^{\circ}\text{C}$
Total Capacitance <sup>1)</sup>	$C$	–	470	–	pF	$V_R=1\text{ V}, f=1\text{ MHz}$
		–	61	–		$V_R=300\text{ V}, f=1\text{ MHz}$
		–	60	–		$V_R=600\text{ V}, f=1\text{ MHz}$

1) Per Leg

2) Per Device

## 4 Electrical characteristics diagrams

Table 7

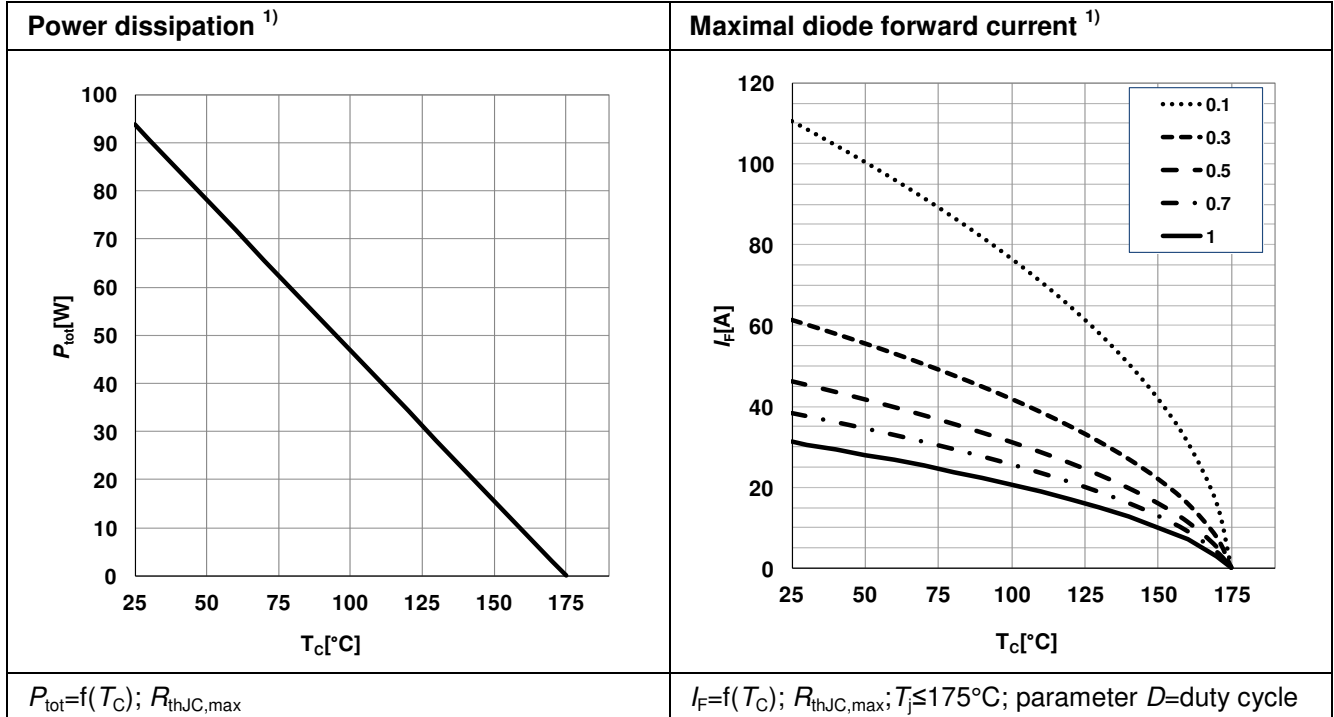
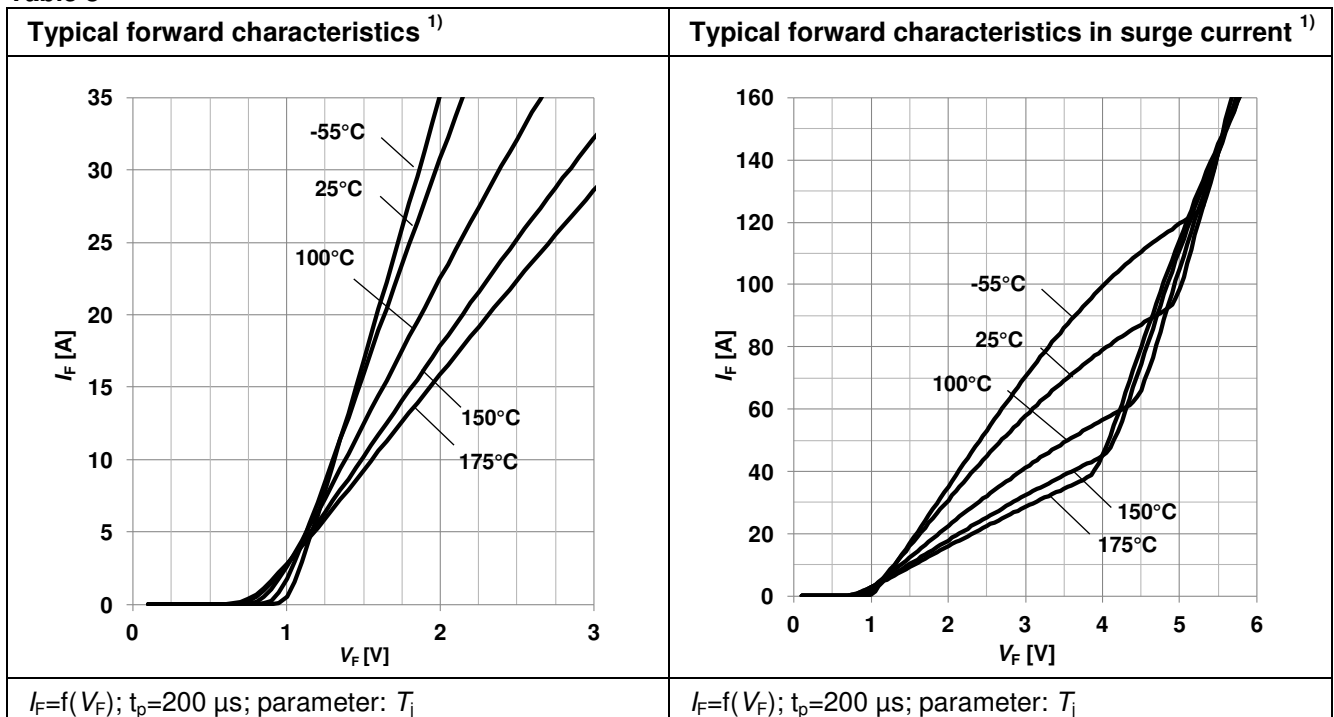


Table 8



1) Per Leg

2) Per Device

Table 9

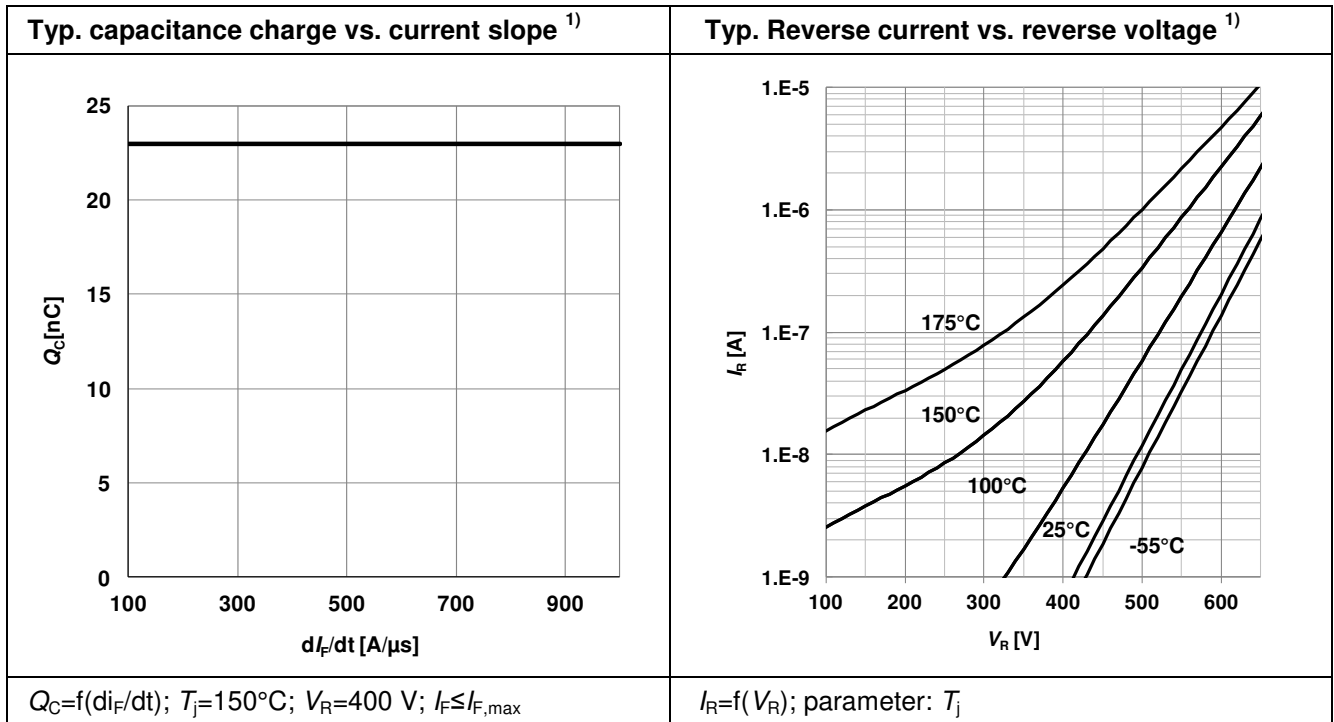
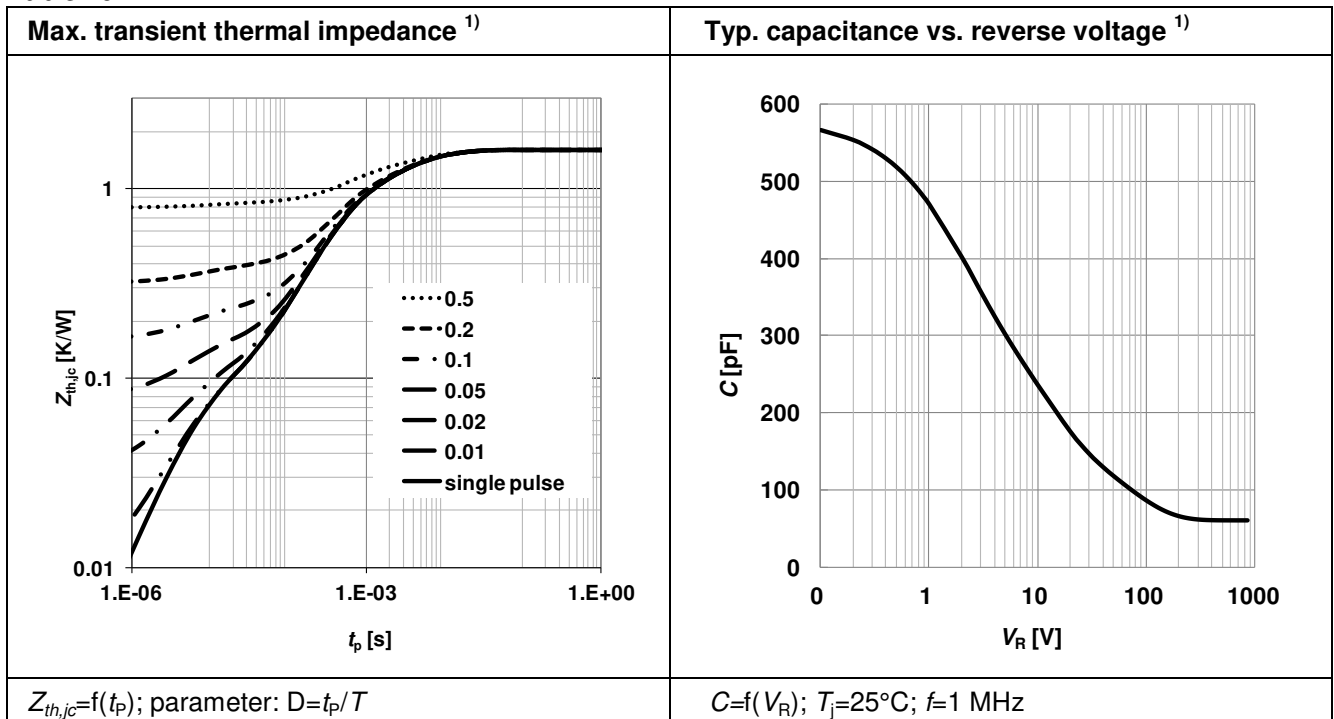


Table 10

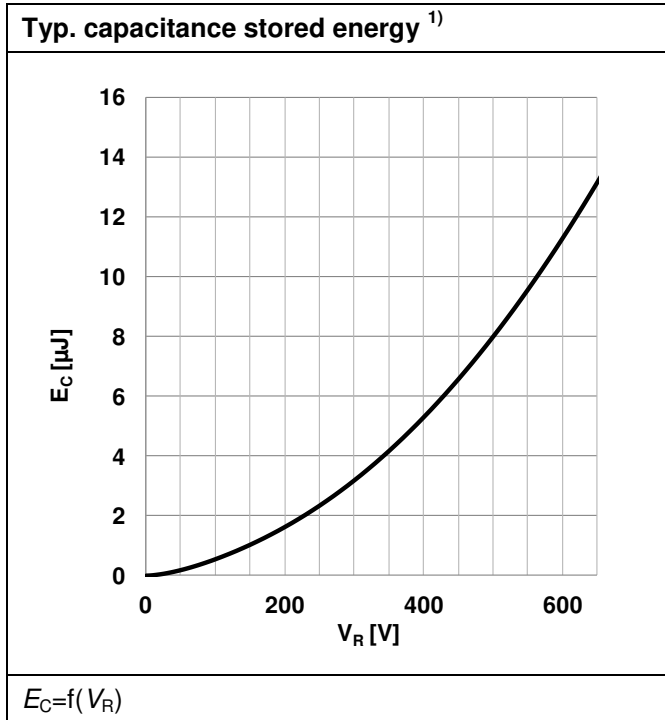


1) Per Leg

2) Per Device

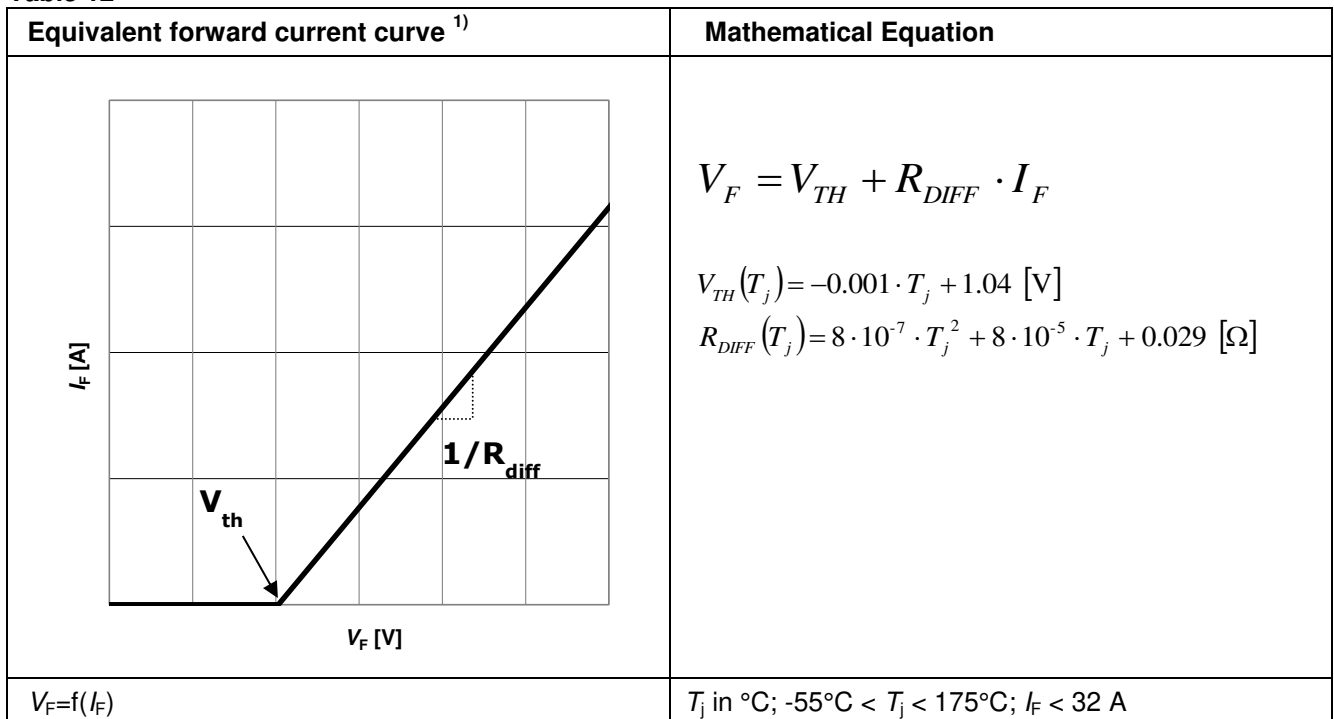


Table 11



## 5 Simplified Forward Characteristics Model

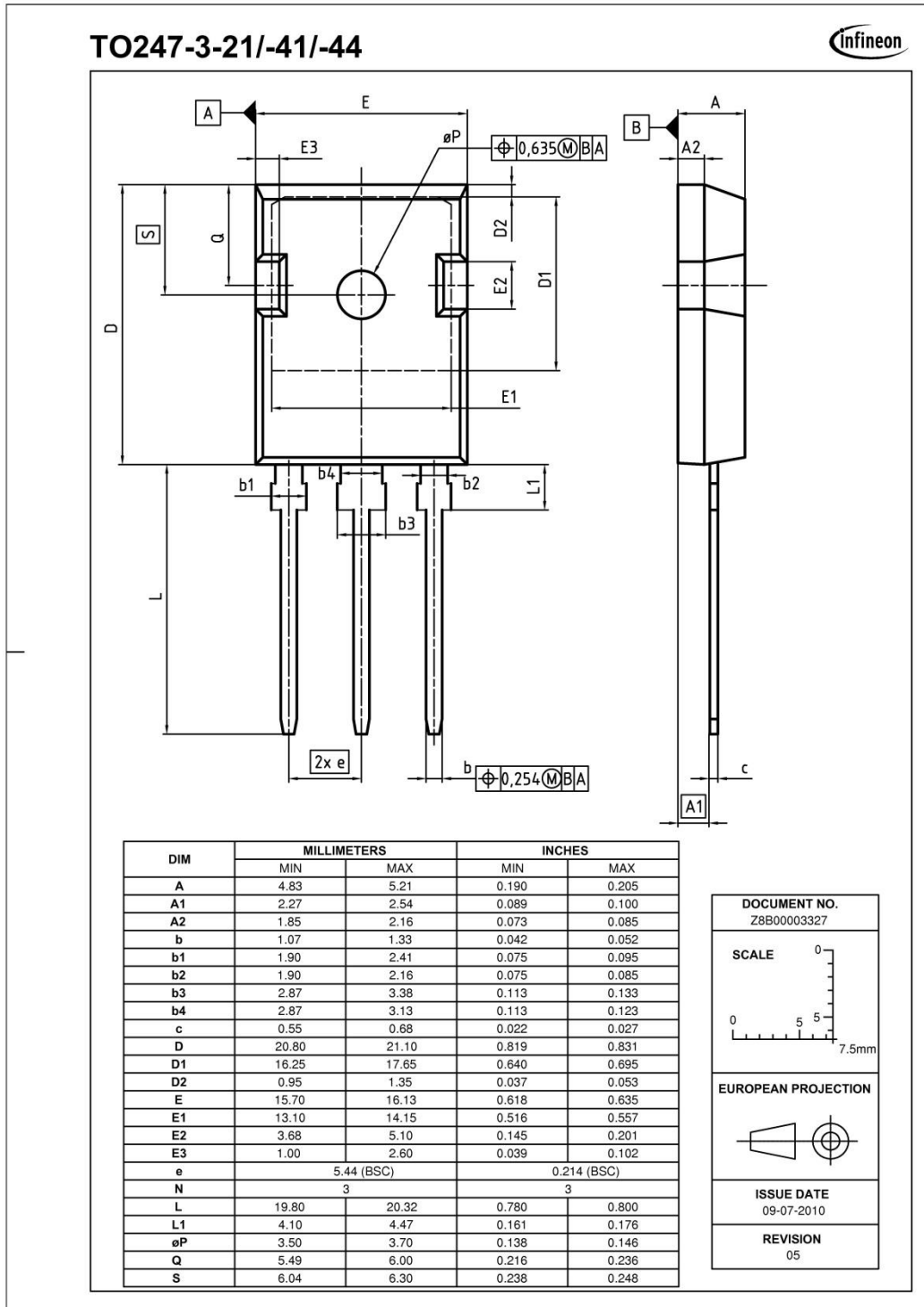
Table 12



1) Per Leg

2) Per Device

## 6 Package outlines



**Figure 1** Outlines TO-247, dimensions in mm/inches

- 1) Per Leg
- 2) Per Device

## 7 Revision History

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### 5<sup>th</sup> Generation thinQ!<sup>TM</sup> SiC Schottky Diode

**Revision History: 2015-04-13, Rev.2.0**

**Previous Revision:**

Revision	Subjects (major changes since last version)
2.0	Release of the final datasheet.

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